



Material Content Data Sheet



Sales Product Name		ESD207-B1-02EL E6327		Issued		19. July 2018		
MA#		MA001310958						
Package		PG-TSLP-2-19		Weight*		0.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.06		578	
	noble metal	gold	7440-57-5	0.001	0.22		2238	
	inorganic material	silicon	7440-21-3	0.010	1.66	1.94	16589	19405
leadframe	non noble metal	nickel	7440-02-0	0.241	39.83	39.83	398257	398257
wire	non noble metal	copper	7440-50-8	0.002	0.39	0.39	3875	3875
encapsulation	organic material	carbon black	1333-86-4	0.002	0.27		2720	
	plastics	epoxy resin	-	0.048	7.89		78877	
	inorganic material	silicondioxide	60676-86-0	0.279	46.24	54.40	462376	543973
leadfinish	noble metal	gold	7440-57-5	0.010	1.72	1.72	17245	17245
plating	noble metal	gold	7440-57-5	0.010	1.72	1.72	17245	17245
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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